

The Manic Depression of Microprocessor Debug

Doug Josephson
*Hewlett Packard
Company*



Presentation Overview

- Challenges of processor debug
- Design features to support debug
- Other tools used in debugging
- Bug example
- Future challenges

Processor Debug is Hard!

- Aggressive circuit design
 - Low margin for errors
- Leading edge processes
 - Very large designs
 - Yield issues
 - Process variation is increasing
 - Lead time (masks/fabrication)
- This means... difficult debug
 - Traditional external debug methods insufficient
 - Design hooks are required for success

Internal Debug Hooks

- Debug triggers
- Scan observability
- Clock manipulation
- Event monitors
- Event injectors
- Hardware error checkers

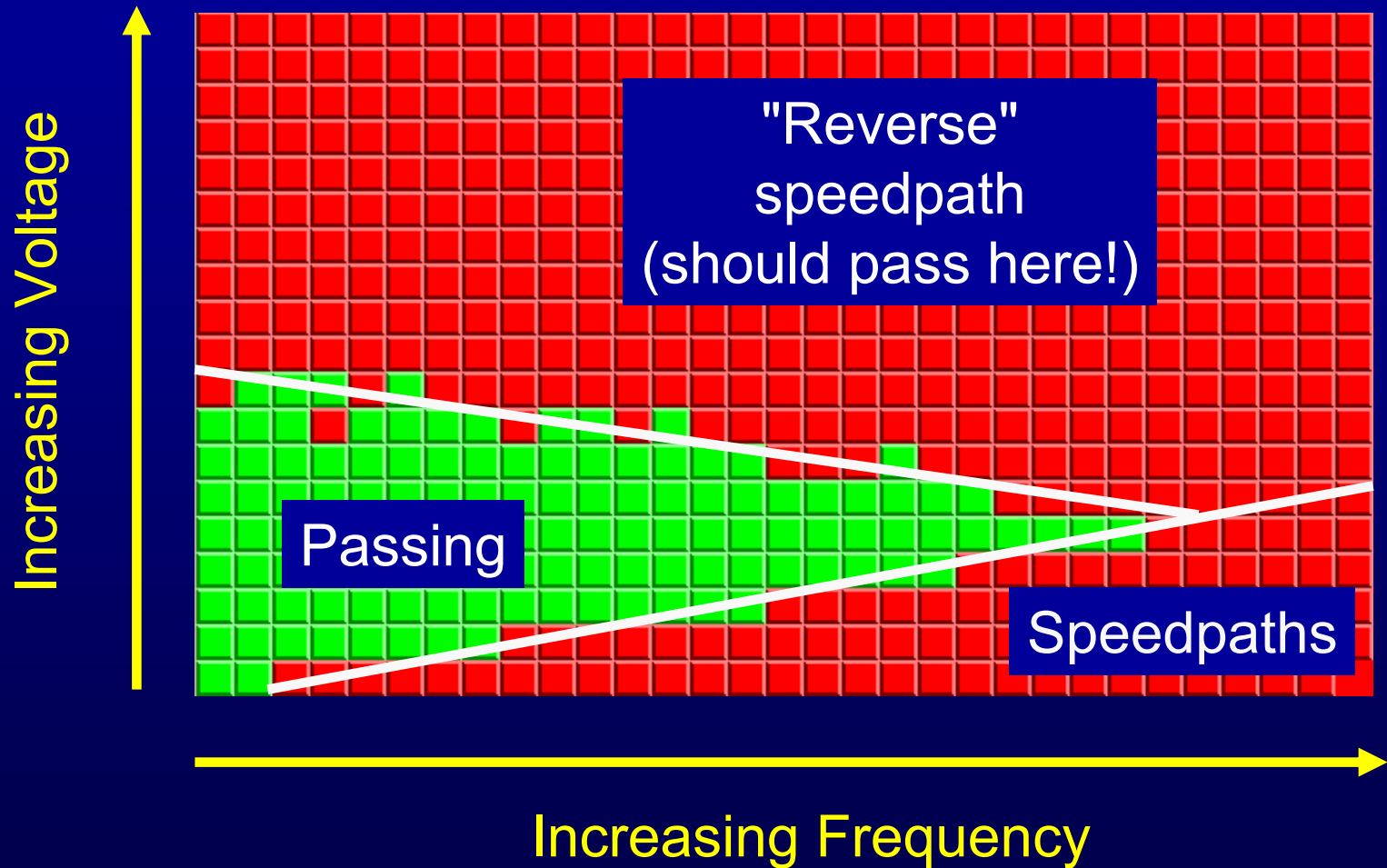
External Debug Aids

- Systems and testers
- Laser Voltage Probe (LVP) and E-beam
- Focused Ion Beam edits (FIB)
- Shmoos
- Code experimentation
 - Random
 - Manual and focused
- SPICE and other design tools

Processor Debug Example

- A failure is sourced in system testing
 - Found during OS testing
 - Isolated to driver code in the OS
- Further isolated to particular sequence
 - Back to back instructions were important
- Code sequence ported to a tester
 - Proof that failure was processor related
 - Failure was worse cold and on fast parts
 - Shmoo demonstrated a "reverse" speedpath

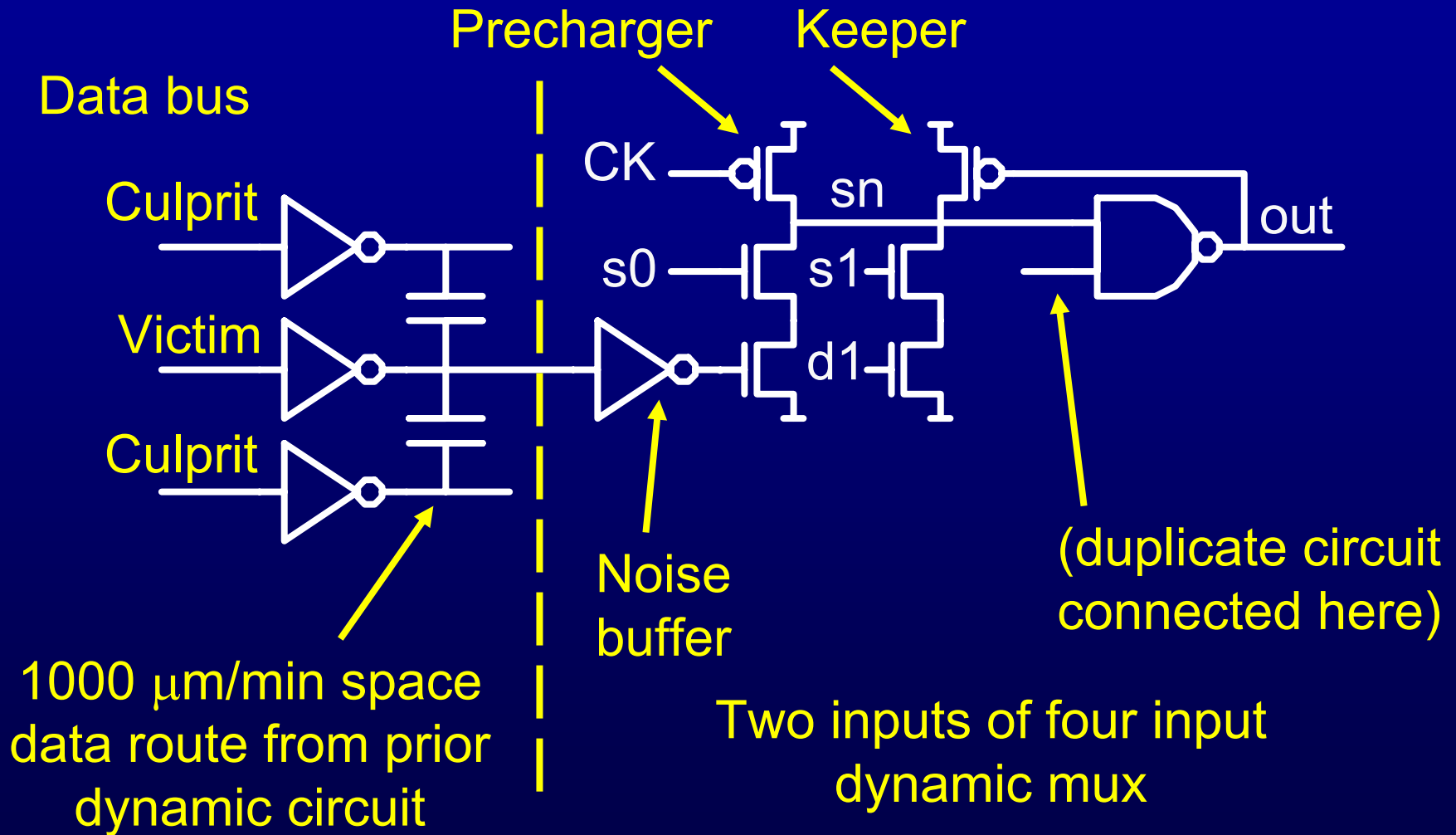
Shmoo Will Be Your Friend (?)

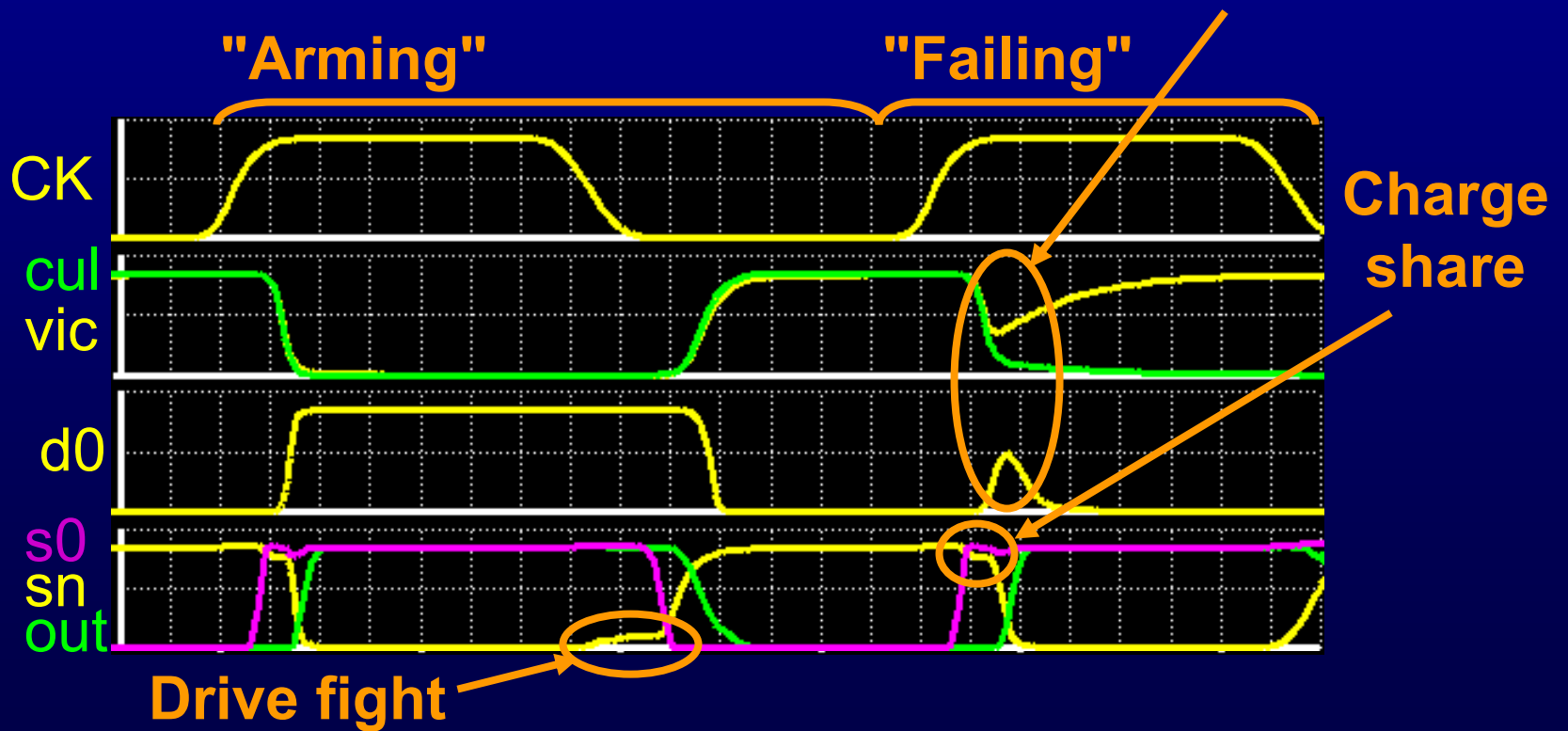
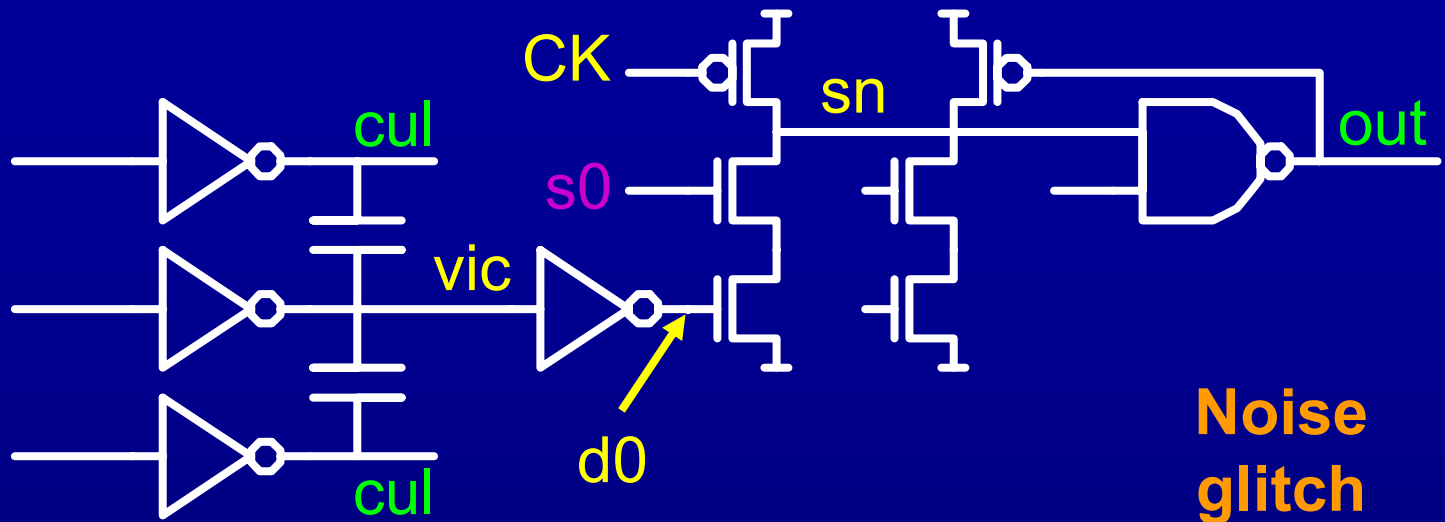


Debug Process

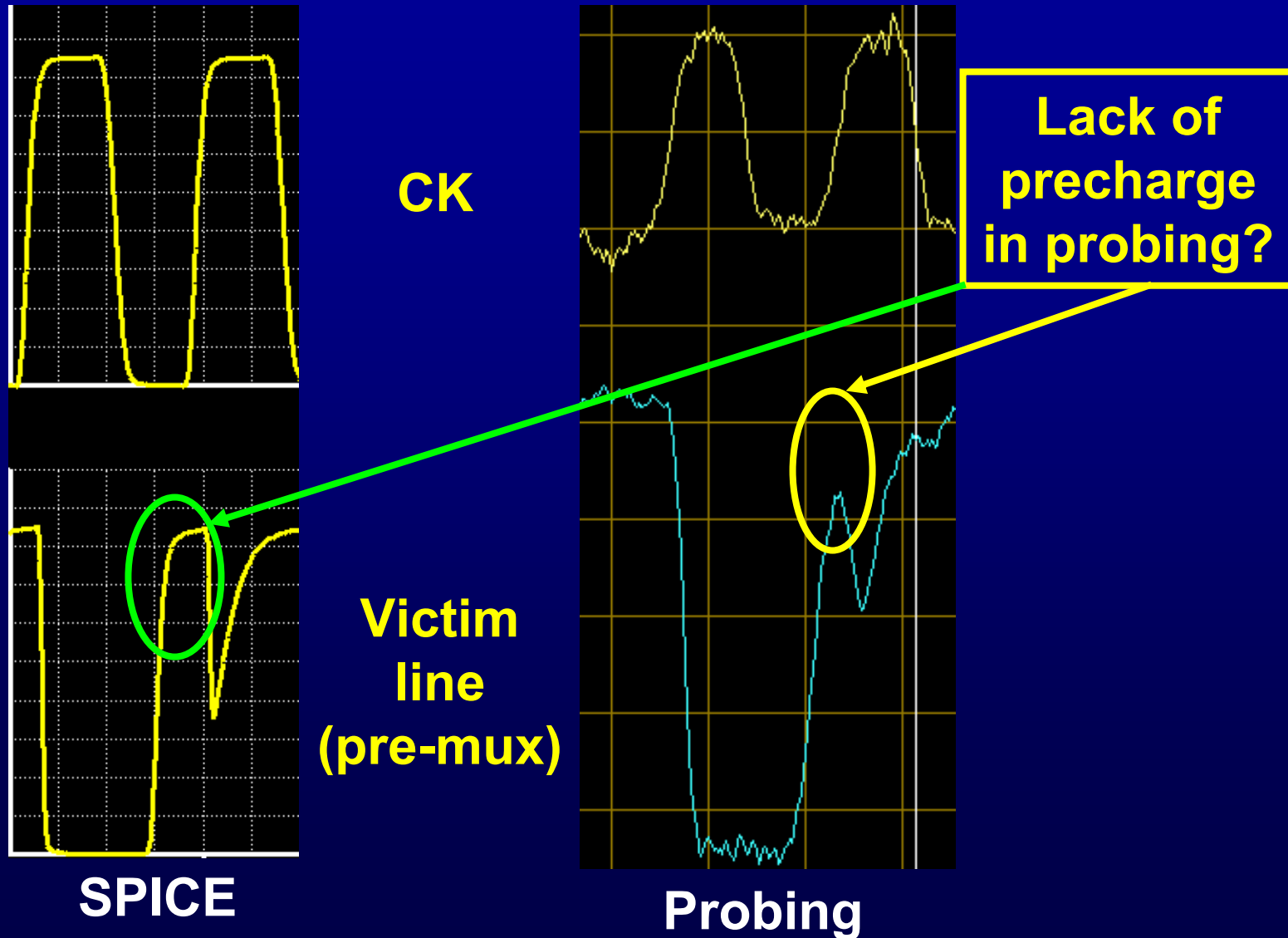
- Debug engineers begin work
 - Code/shmoo experiments
 - Scan/clock manipulation
- A suspect circuit is found
 - Based upon instructions executed by unit
 - Circuit has little noise margin
 - Circuit also has marginal precharge
 - Focus narrows to artwork/SPICE

Suspect - Dynamic Mux

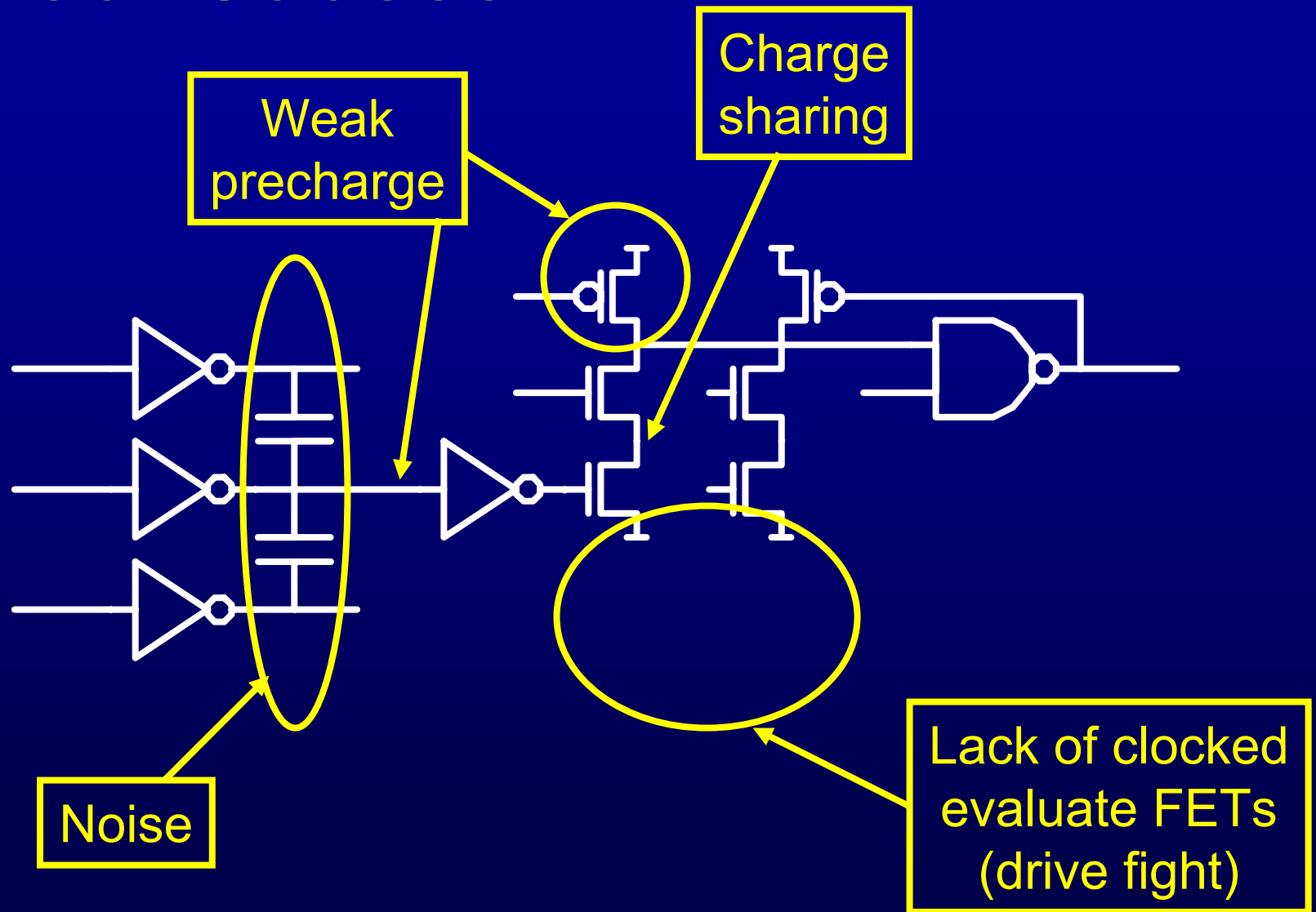




SPICE vs. Probing Results

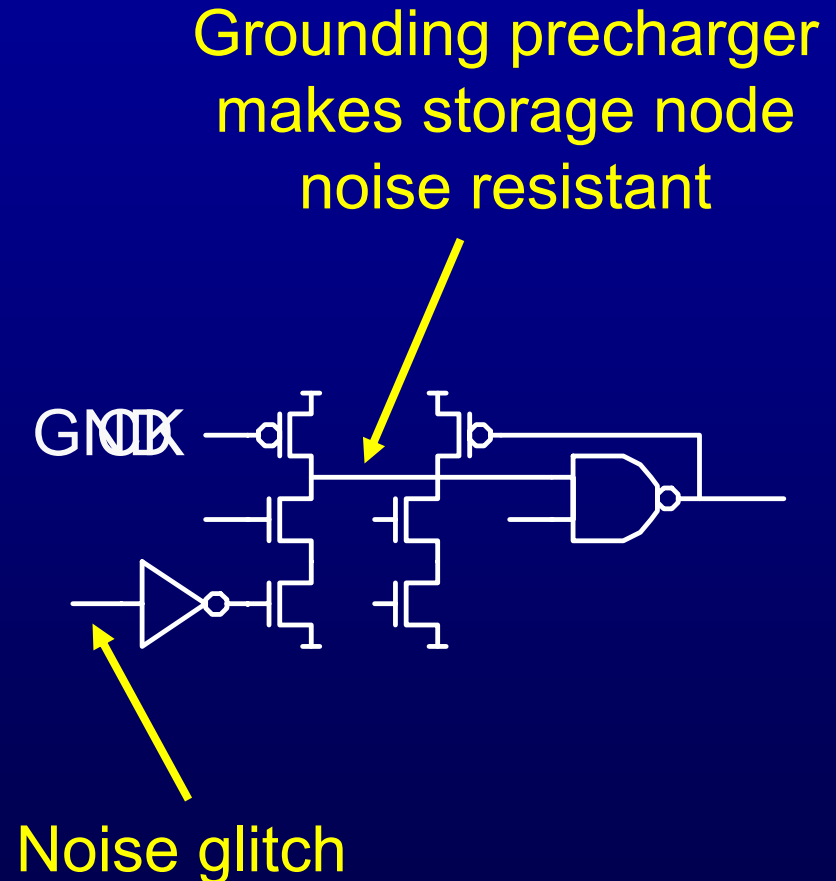


Root Causes

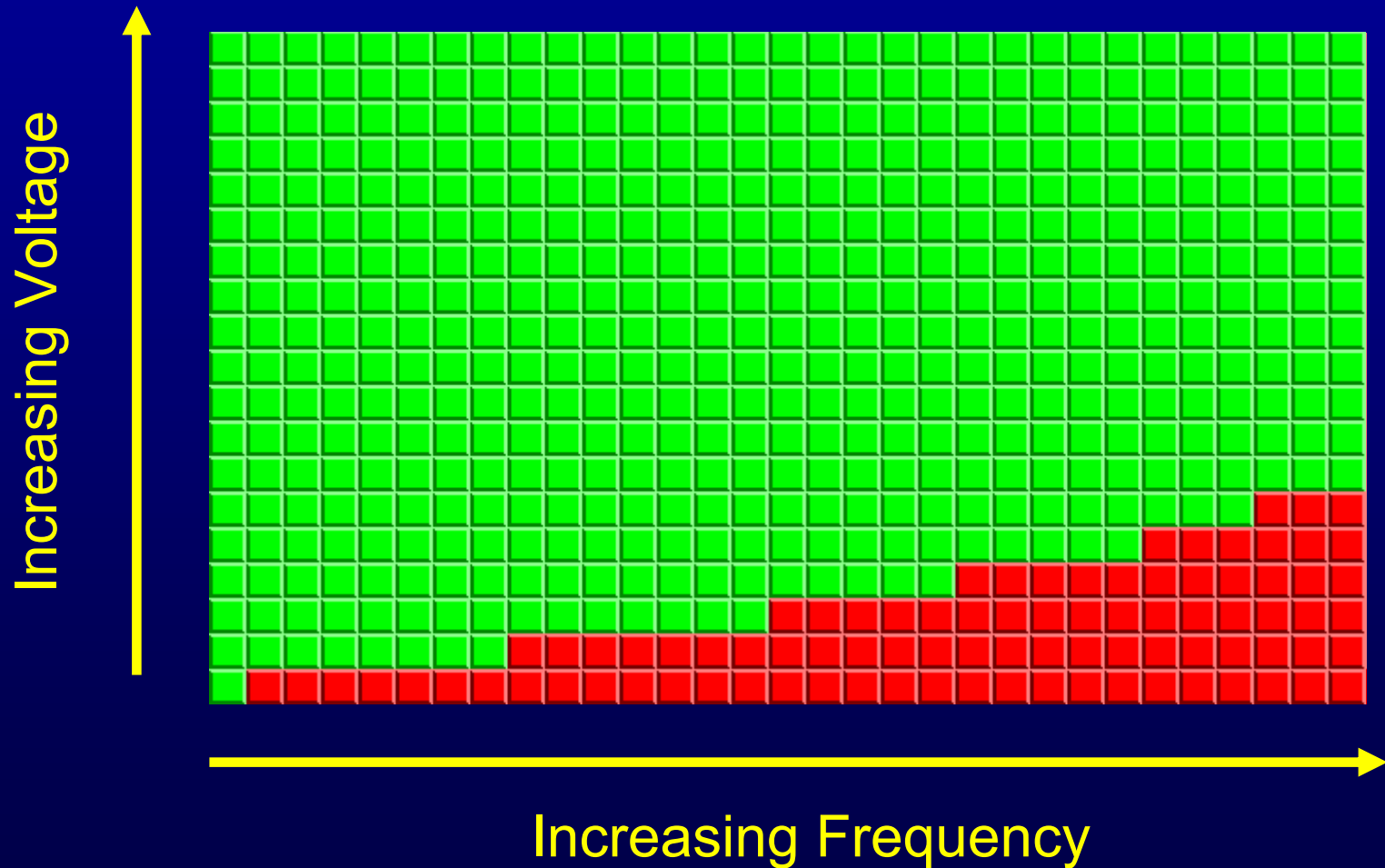


FIB to the Rescue

- A fix is proposed
 - Convert the circuit to pseudo-NMOS
 - Provides noise resistance and addresses precharge and charge sharing
 - Little speed impact
- A FIB edit was performed to test the fix...



Before... and after!



Conclusion - Future Challenges

- Power control
 - Thermal issues
 - Variable operation per part/between parts
- High-speed interfaces
 - 2-4 GT/s with high pin counts
 - Beyond ATE capabilities for processors!
- Repeatability
- Process variation/lithography